Chipsmall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832
Email & Skype: info@chipsmall.com Web: www.chipsmall.com
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

VNH5019A-E

Automotive fully integrated H-bridge motor driver

MultiPowerSO-30™

Features

Type	$R_{DS(on)}$	I_{out}	V_{ccmax}
VNH5019A-E	18 mΩ typ (per leg)	30 A	41 V

- AEC-Q100 qualified
- ECOPACK®: lead free and RoHS compliant
- Output current: 30 A
- 3 V CMOS compatible inputs
- Undervoltage and overvoltage shutdown
- High-side and low-side thermal shutdown
- Cross-conduction protection
- Current limitation
- Very low standby power consumption
- PWM operation up to 20 kHz
- Protection against:
- Loss of ground and loss of V_{CC}
- Current sense output proportional to motor current
- Charge pump output for reverse polarity protection
- Output protected against short to ground and short to V_{CC}

Description

The VHN5019A-E is a full bridge motor driver intended for a wide range of automotive applications. The device incorporates a dual monolithic high-side drivers and two low-side switches. The high-side driver switch is designed using STMicroelectronics' well known and proven proprietary VIPower® M0 technology that allows to efficiently integrate on the same die a true Power MOSFET with an intelligent signal/protection circuit.

The three dice are assembled in a MultiPowerSO-30 package on electrically isolated lead-frames. This package, specifically designed for harsh automotive environments offers improved thermal performance thanks to exposed die pads. The input signals IN_A and IN_B can directly interface to the microcontroller to select the motor direction and the brake condition.

The $DIAG_A/EN_A$ or $DIAG_B/EN_B$, when connected to an external pull-up resistor, enable one leg of the bridge. They also provide a feedback digital diagnostic signal. The CS pin allows to monitor the motor current by delivering a current proportional to its value when CS_DIS pin is driven low or left open. The PWM, up to 20 KHz, lets us to control the speed of the motor in all possible conditions. In all cases, a low-level state on the PWM pin turns off both the LS_A and LS_B switches. When PWM rises to a high-level, LS_A or LS_B turn-on again depending on the input pin state. Output current limitation and thermal shutdown protects the concerned high-side in short to ground condition.

The short to battery condition is revealed by the overload detector or by thermal shutdown that latches off the relevant low-side.

Active V_{CC} pin voltage clamp protects the device against low energy spikes in all configurations for the motor. The CP pin provides the necessary gate drive for an external N-channel PowerMOS used for reverse polarity protection.

Contents

List of tables

List of figures

1   Block diagram and pin description

Figure 1. Block diagram
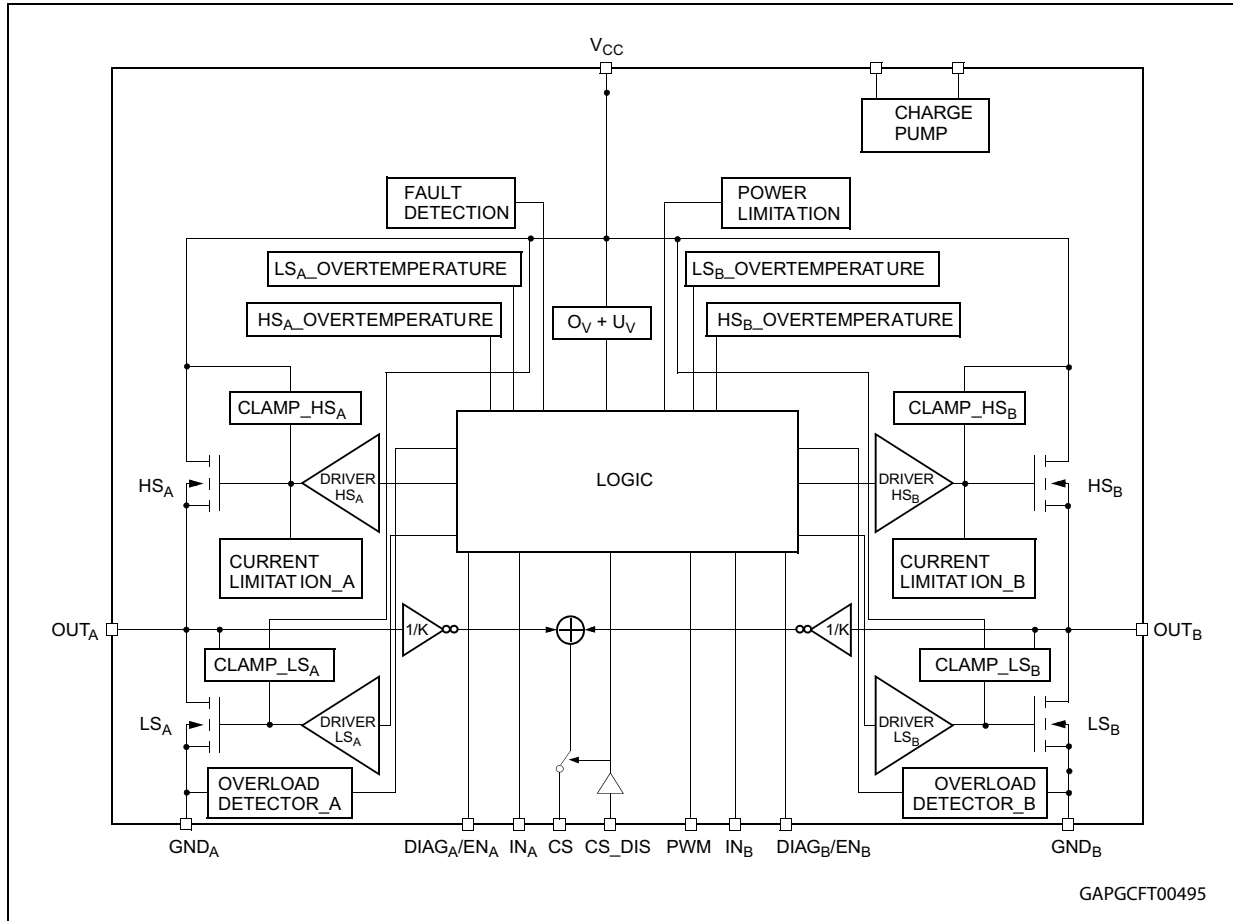
Figure 2. Configuration diagram (top view)
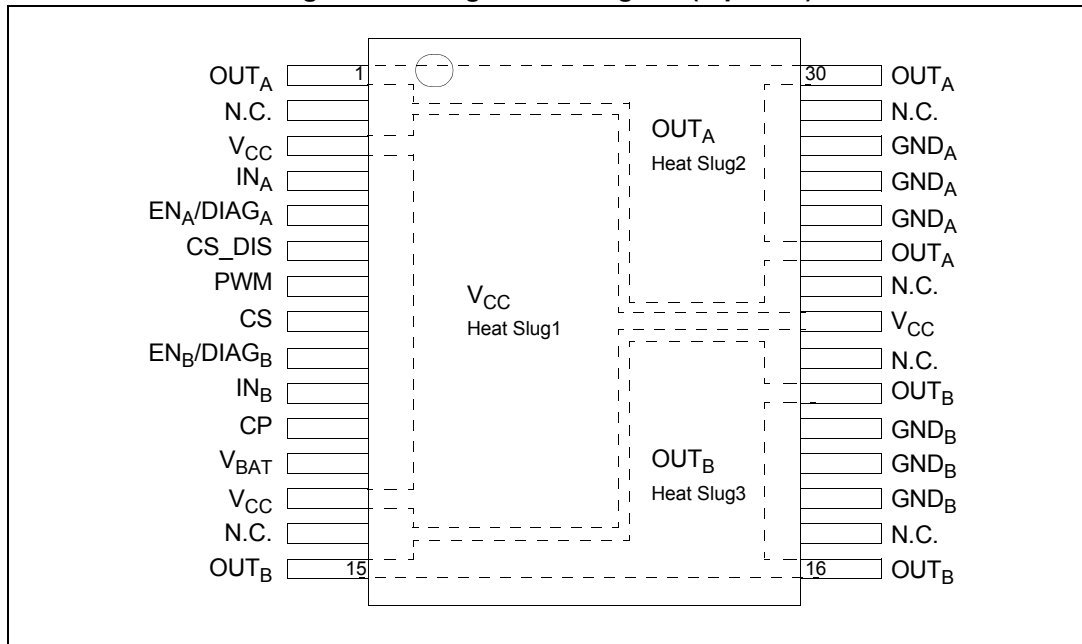
Table 1. Suggested connections for unused and non connected pins

Connection / pin	Current sense	N.C.	OUTx	INPUTx, PWM DIAGx/ENx CS_DIS
Floating	Not allowed	X	X	X
To ground	Through 1 kΩ resistor	X	Not allowed	Through 10 kΩ resistor

Table 2. Pin definitions and functions

Pin	Symbol	Function
1, 25, 30	OUT$_A$, Heat Slug2	Source of high-side switch A / drain of low-side switch A, power connection to the motor
2,14,17, 22, 24,29	N.C.	Not connected
3, 13, 23	V$_{CC}$, Heat Slug1	Drain of high-side switches and connection to the drain of the external PowerMOS used for the reverse battery protection
12	V$_{BAT}$	Battery connection and connection to the source of the external PowerMOS used for the reverse battery protection
5	EN$_A$/DIAG$_A$	Status of high-side and low-side switches A; open drain output. This pin must be connected to an external pull-up resistor. When externally pulled low, it disables half-bridge A. In case of fault detection (thermal shutdown of a high-side FET or excessive ON-state voltage drop across a low-side FET), this pin is pulled low by the device (see *Table 13: Truth table in fault conditions (detected on OUTA).*

Table 2. Pin definitions and functions (continued)

Pin	Symbol	Function
6	CS_DIS	Active high CMOS compatible pin to disable the current sense pin
4	IN$_A$	Clockwise input. CMOS compatible
7	PWM	PWM input. CMOS compatible.
8	CS	Output of current sense. This output delivers a current proportional to the motor current, if CS_DIS is low or left open. The information can be read back as an analog voltage across an external resistor.
9	EN$_B$/DIAG$_B$	Status of high-side and low-side switches B; Open drain output. This pin must be connected to an external pull up resistor. When externally pulled low, it disables half-bridge B. In case of fault detection (thermal shutdown of a high-side FET or excessive ON-state voltage drop across a low-side FET), this pin is pulled low by the device (see *Table 13: Truth table in fault conditions (detected on OUTA)*.
10	IN$_B$	Counter clockwise input. CMOS compatible
11	CP	Connection to the gate of the external MOS used for the reverse battery protection
15, 16, 21	OUT$_B$, Heat Slug3	Source of high-side switch B / drain of low-side switch B, power connection to the motor
26, 27, 28	GND$_A$	Source of low-side switch A and power ground[1]
18, 19, 20	GND$_B$	Source of low-side switch B and power ground[1]

1. GNDA and GNDB must be externally connected together

Table 3. Block descriptions[1]

Name	Description
Logic control	Allows the turn-on and the turn-off of the high-side and the low-side switches according to the *Table 12*.
Overvoltage + undervoltage	Shut down the device outside the range [4.5 V to 24 V] for the battery voltage.
High-side, low-side and clamp voltage	Protect the high-side and the low-side switches from the high-voltage on the battery line in all configuration for the motor.
High-side and low-side driver	Drive the gate of the concerned switch to allow a proper R$_{DS(on)}$ for the leg of the bridge.
Linear current limiter	Limits the motor current, by reducing the high-side switch gate-source voltage when short-circuit to ground occurs.
High-side and low-side overtemperature protection	In case of short-circuit with the increase of the junction temperature, it shuts down the concerned driver to prevent its degradation and to protect the die.
Low-side overload detector	Detects when low-side current exceeds shutdown current and latches off the concerned low-side.

Name	Description
Charge pump	Provides the voltage necessary to drive the gate of the external PowerMOS used for the reverse polarity protection
Fault detection	Signalizes an abnormal condition of the switch (output shorted to ground or output shorted to battery) by pulling down the concerned ENx/DIAGx pin.
Power limitation	Limits the power dissipation of the high-side driver inside safe range in case of short to ground condition.

1. See *Figure 1*

2   Electrical specifications

Figure 3. Current and voltage conventions
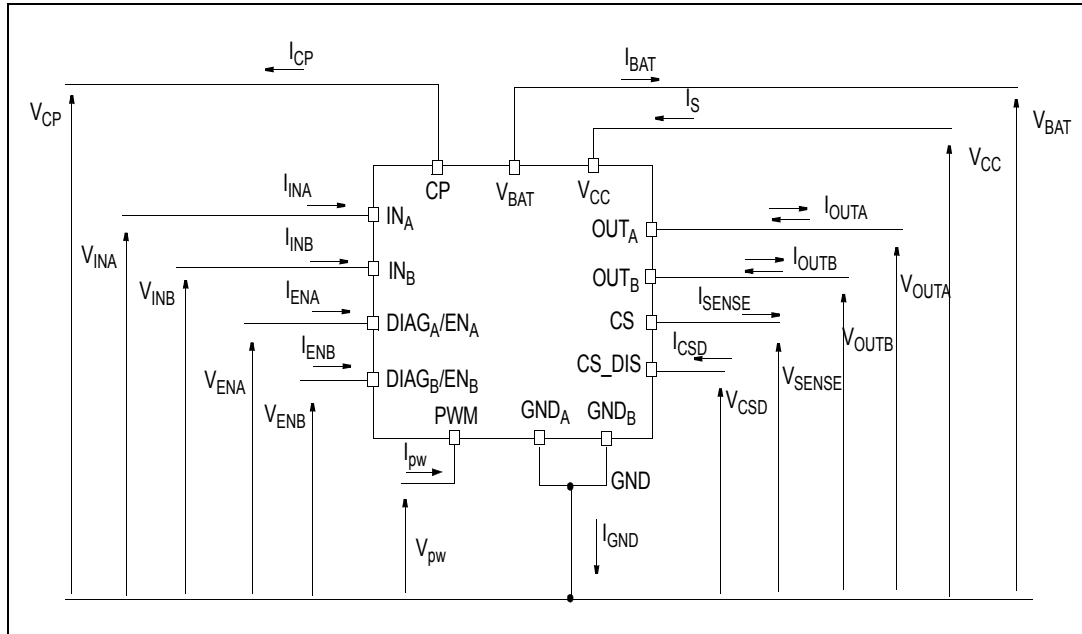
2.1   Absolute maximum ratings

Stressing the device above the rating listed in the "absolute maximum ratings" table may cause permanent damage to the device. These are stress ratings only and operation of the device at these or any other conditions above those indicated in the operating sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Refer also to the STMicroelectronics SURE program and other relevant quality document.

Table 4. Absolute maximum rating

Symbol	Parameter	Value	Unit
V_{BAT}	Maximum battery voltage[(1)]	-16	V
		+41	V
V_{CC}	Maximum bridge supply voltage	+ 41	V
I_{max}	Maximum output current (continuous)	30	A
I_R	Reverse output current (continuous)	-30	A
I_{IN}	Input current (IN_A and IN_B pins)	+/- 10	mA
I_{EN}	Enable input current ($DIAG_A/EN_A$ and $DIAG_B/EN_B$ pins)	+/- 10	mA
I_{pw}	PWM input current	+/- 10	mA
I_{CP}	CP output current	+/- 10	mA
I_{CS_DIS}	CS_DIS input current	+/- 10	mA

Table 4. Absolute maximum rating (continued)

Symbol	Parameter	Value	Unit
V_{CS}	Current sense maximum voltage	V_{CC} - 41 +V_{CC}	V V
V_{ESD}	Electrostatic discharge (human body model: R = 1.5 kΩ, C = 100 pF)	2	kV
T_c	Case operating temperature	-40 to 150	°C
T_{STG}	Storage temperature	-55 to 150	°C

1. This applies with the n-channel MOSFET used for the reverse battery protection. Otherwise V_{BAT} has to be shorted to V_{CC}.

2.2 Thermal data

Table 5. Thermal data

Symbol	Parameter	Max. value	Unit
$R_{thj\text{-}case}$	Thermal resistance junction-case HSD	1.7	°C/W
	Thermal resistance junction-case LSD	3.2	°C/W
$R_{thj\text{-}amb}$	Thermal resistance junction-ambient	See *Figure 18*	°C/W

2.3 Electrical characteristics

Values specified in this section are for 8 V < V_{CC} < 21 V, -40 °C < T_j < 150 °C, unless otherwise specified.

Table 6. Power section

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V_{CC}	Operating bridge supply voltage		5.5		24	V
I_S	Supply current	OFF-state with all fault cleared and ENx = 0 V (standby): $IN_A = IN_B$ = PWM = 0; T_j = 25 °C; V_{CC} = 13 V $IN_A = IN_B$ = PWM = 0 OFF-state (no standby): $IN_A = IN_B$ = PWM = 0; ENx = 5 V		10	15 60 6	µA µA mA
		ON-state: IN_A or IN_B = 5 V, no PWM IN_A or IN_B = 5 V, PWM = 20 kHz		4	8 8	mA mA
R_{ONHS}	Static high-side resistance	I_{OUT} = 15 A; T_j = 25 °C		12.0		mΩ
		I_{OUT} = 15 A; T_j = - 40 °C to 150 °C			26.5	
R_{ONLS}	Static low-side resistance	I_{OUT} = 15 A; T_j = 25 °C		6.0		mΩ
		I_{OUT} = 15 A; T_j = - 40 °C to 150 °C			11.5	
V_f	High-side free-wheeling diode forward voltage	I_f = 15 A, T_j = 150 °C		0.6	0.8	V
$I_{L(off)}$	High-side OFF-state output current (per channel)	T_j = 25 °C; $V_{OUTX} = EN_X$ = 0 V; V_{CC} = 13 V			3	µA
		T_j = 125 °C; $V_{OUTX} = EN_X$ = 0 V; V_{CC} = 13 V			5	

Table 7. Logic inputs (IN_A, IN_B, EN_A, EN_B, PWM, CS_DIS)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V_{IL}	Low-level input voltage	Normal operation ($DIAG_X/EN_X$ pin acts as an input pin)			0.9	V
V_{IH}	High-level input voltage	Normal operation ($DIAG_X/EN_X$ pin acts as an input pin)	2.1			V
I_{INL}	Low-level input current	V_{IN} = 0.9 V	1			µA
I_{INH}	High-level input current	V_{IN} = 2.1 V			10	µA
V_{IHYST}	Input hysteresis voltage	Normal operation ($DIAG_X/EN_X$ pin acts as an input pin)	0.15			V

Table 7. Logic inputs (IN$_A$, IN$_B$, EN$_A$, EN$_B$,PWM, CS_DIS) (continued)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V$_{ICL}$	Input clamp voltage	I$_{IN}$ = 1 mA	5.5	6.3	7.5	V
		I$_{IN}$ = -1 mA	-1.0	-0.7	-0.3	
V$_{DIAG}$	Enable low-level output voltage	Fault operation (DIAG$_X$/EN$_X$ pin acts as an output pin); I$_{EN}$ = 1 mA			0.4	V

Table 8. Switching (V$_{CC}$ = 13 V, R$_{LOAD}$ = 0.87 Ω, Tj = 25 °C)

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
f	PWM frequency		0		20	kHz
t$_{d(on)}$	HSD rise time	Input rise time < 1µs (see *Figure 9*)			250	µs
t$_{d(off)}$	HSD fall time	Input rise time < 1µs (see *Figure 9*)			250	µs
t$_r$	LSD rise time	(see *Figure 8*)		1	2	µs
t$_f$	LSD fall time	(see *Figure 8*)		1	2	µs
t$_{DEL}$	Delay time during change of operating mode	(see *Figure 7*)	200	400	1600	µs
t$_{rr}$	High-side free wheeling diode reverse recovery time	(see *Figure 10*)		110		ns
I$_{RM}$	Dynamic cross-conduction current	I$_{OUT}$ = 15 A (see *Figure 10*)		2		A

Table 9. Protection and diagnostic

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
V$_{USD}$	V$_{CC}$ undervoltage shutdown			4.5	5.5	V
V$_{USDhyst}$	V$_{CC}$ undervoltage shutdown hysteresis			0.5		V
V$_{OV}$	V$_{CC}$ overvoltage shutdown		24	27	30	V
I$_{LIM\_H}$	High-side current limitation		30	50	70	A
I$_{SD\_LS}$	Low-side shutdown current		70	115	160	A
V$_{CLPHS}$[1]	High-side clamp voltage (V$_{CC}$ to OUT$_A$ = 0 or OUT$_B$ = 0)	I$_{OUT}$ = 15 A	43	48	54	V
V$_{CLPLS}$[1]	Low-side clamp voltage (OUT$_A$ = V$_{CC}$ or OUT$_B$ = V$_{CC}$ to GND)	I$_{OUT}$ = 15 A	27	30	33	V
T$_{TSD}$[2]	Thermal shutdown temperature	V$_{IN}$ = 2.1 V	150	175	200	°C

Table 9. Protection and diagnostic (continued)

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
T_{TSD_LS}	Low-side thermal shutdown temperature	V_{IN} = 0 V	150	175	200	°C
T_{TR}[3]	Thermal reset temperature		135			°C
T_{HYST}[3]	Thermal hysteresis		7	15		°C

1. The device is able to pass the ESD and ISO pulse requirements as specified in the *Table 15*.

2. T_{TSD} is the minimum threshold temperature between HS and LS

3. Valid for both HSD and LSD

Table 10. Current sense (8 V < V_{CC} < 21 V)

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
K_0	I_{OUT}/I_{SENSE}	I_{OUT} = 3 A, V_{SENSE} = 0.5 V, T_j = - 40 °C to 150°C	4670	7110	10110	
dK_0/K_0	Analog current sense ratio drift	I_{OUT} = 3 A; V_{SENSE} = 0.5 V, T_j = -40 °C to 150 °C	-19		19	%
K_1	I_{OUT}/I_{SENSE}	I_{OUT} = 8 A, V_{SENSE} = 1.3V, T_j = - 40 °C to 150°C	6060	7030	8330	
dK_1/K_1	Analog current sense ratio drift	I_{OUT} = 8 A; V_{SENSE} = 1.3V, T_j = -40 °C to 150 °C	-14		14	%
K_2	I_{OUT}/I_{SENSE}	I_{OUT} = 15 A, V_{SENSE} = 2.4 V, T_j = - 40 °C to 150°C	6070	6990	7810	
dK_2/K_2	Analog current sense ratio drift	I_{OUT} = 15 A; V_{SENSE} = 2.4 V, T_j = -40 °C to 150 °C	-12		12	%
K_3	I_{OUT}/I_{SENSE}	I_{OUT} = 25 A, V_{SENSE} = 4 V, T_j = - 40 °C to 150°C	6000	6940	7650	
dK_3/K_3	Analog current sense ratio drift	I_{OUT} =25 A; V_{SENSE} = 4 V, T_j = -40 °C to 150 °C	-12		12	%
V_{SENSE}	Max analog sense output voltage	I_{OUT} = 15 A, R_{SENSE} = 1.1 kΩ	5			V
I_{SENSEO}	Analog sense leakage current	I_{OUT} = 0 A, V_{SENSE} = 0 V, V_{CSD} = 5 V, V_{IN} = 0 V, T_j = - 40 to 150°C	0		5	µA
		I_{OUT} = 0 A, V_{SENSE} = 0 V, V_{CSD} = 0 V, V_{IN} = 5 V, T_j = - 40 to 150°C	0		100	
$t_{DSENSEH}$	Delay response time from falling edge of CS_DIS pin	V_{IN} = 5 V, V_{SENSE} < 4 V, I_{OUT} = 8 A, I_{SENSE} = 90% of $I_{SENSEmax}$ (see fig *Figure 13*)			50	µs
$t_{DSENSEL}$	Delay response time from rising edge of CS_DIS pin	V_{IN} = 5 V, V_{SENSE} < 4 V, I_{OUT} = 8 A, I_{SENSE} = 10% of $I_{SENSEmax}$ (see fig *Figure 13*)			20	µs

Table 11. Charge pump

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
V_{CP}	Charge pump output voltage	$EN_X = 5$ V	$V_{CC} + 5$		$V_{CC} + 10$	V
		$EN_X = 5$ V, $V_{CC} = 4.5$ V		10.5		
I_{BAT}	Charge pump standby current	$EN_A = EN_B = 0$ V		200		nA

2.4 Waveforms and truth table

In normal operating conditions the $DIAG_X/EN_X$ pin is considered as an input pin by the device. This pin must be externally pulled-high
PWM pin usage: in all cases, a "0" on the PWM pin turns-off both LS_A and LS_B switches. When PWM rises back to "1", LS_A or LS_B turn-on again depending on the input pin state.

Table 12. Truth table in normal operating conditions

IN_A	IN_B	$DIAG_A/EN_A$	$DIAG_B/EN_B$	OUT_A	OUT_B	CS ($V_{CSD} = 0$ V)	Operating mode
1	1	1	1	H	H	High imp.	Brake to V_{CC}
1	0	1	1	H	L	$I_{SENSE} = I_{OUT}/K$	Clockwise (CW)
0	1	1	1	L	H	$I_{SENSE} = I_{OUT}/K$	Counterclockwise (CCW)
0	0	1	1	L	L	High imp.	Brake to GND

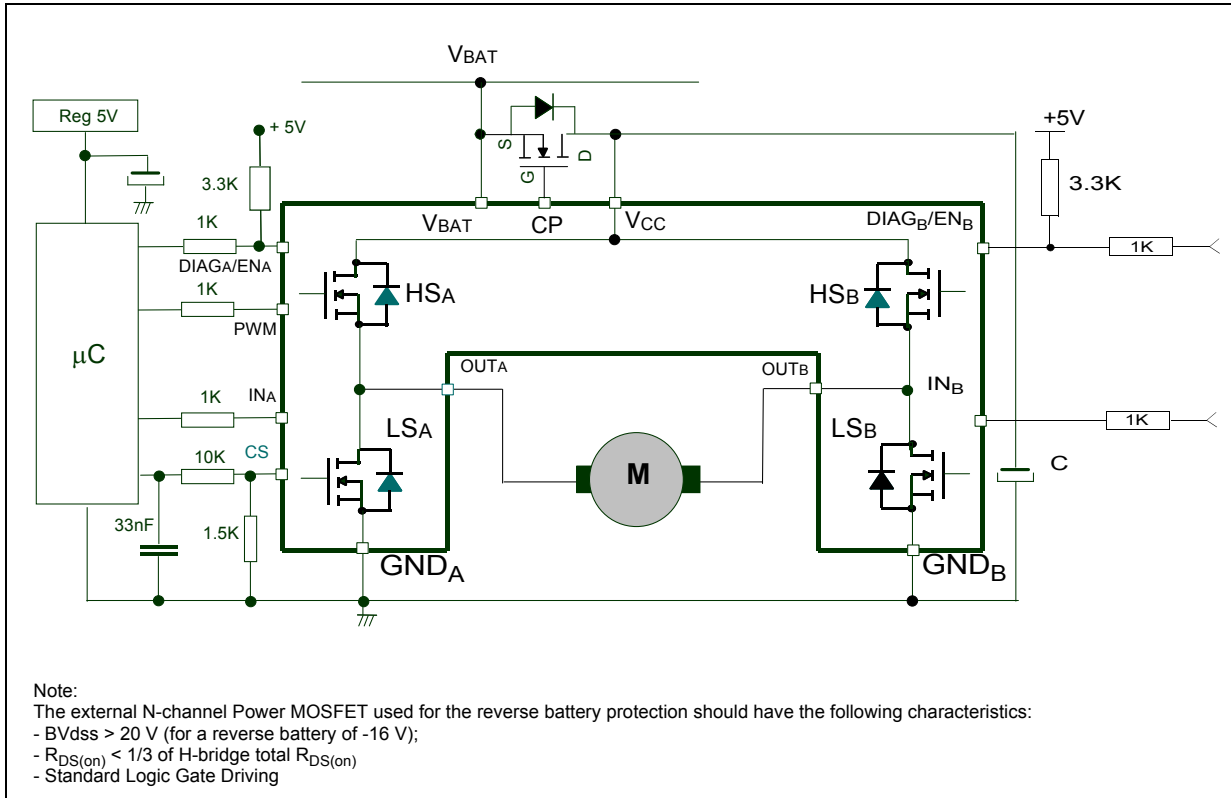**Figure 4. Typical application circuit for DC to 20 kHz PWM operation with reverse battery protection (option A)**

Note:
The external N-channel Power MOSFET used for the reverse battery protection should have the following characteristics:
- BVdss > 20 V (for a reverse battery of -16 V);
- $R_{DS(on)}$ < 1/3 of H-bridge total $R_{DS(on)}$
- Standard Logic Gate Driving

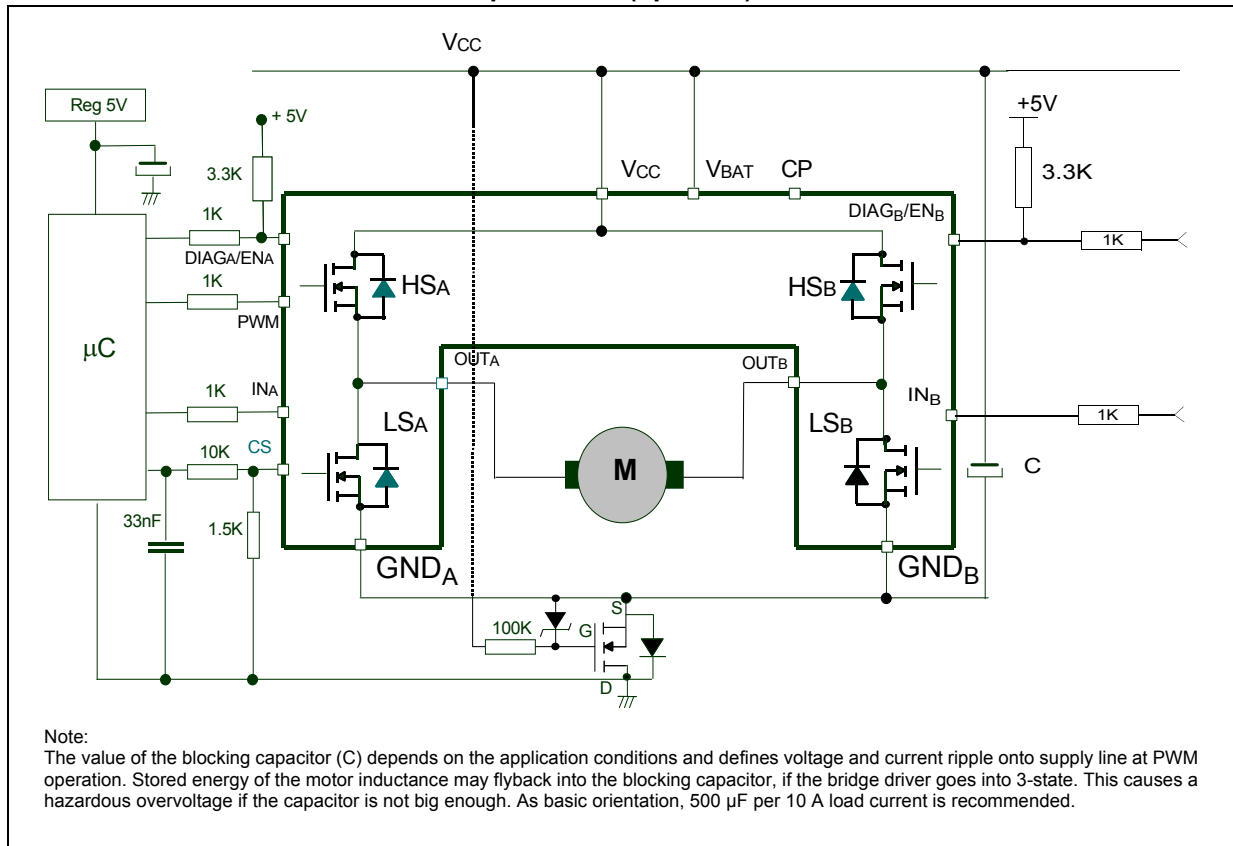**Figure 5. Typical application circuit for DC to 20 kHz PWM operation with reverse battery protection (option B)**

Note:
The value of the blocking capacitor (C) depends on the application conditions and defines voltage and current ripple onto supply line at PWM operation. Stored energy of the motor inductance may flyback into the blocking capacitor, if the bridge driver goes into 3-state. This causes a hazardous overvoltage if the capacitor is not big enough. As basic orientation, 500 µF per 10 A load current is recommended.

Table 13. Truth table in fault conditions (detected on OUT$_A$)

IN$_A$	IN$_B$	DIAG$_A$/EN$_A$	DIAG$_B$/EN$_B$	OUT$_A$	OUT$_B$	CS (V$_{CSD}$=0V)
1	1	0	1	OPEN	H	High impedance
	0				L	
0	1				H	I$_{OUTB}$/K
	0				L	High impedance
X	X		0		OPEN	

Fault Information | Protection Action

Note: *In normal operating conditions the DIAG$_X$/EN$_X$ pin is considered an input pin by the device. This pin must be externally pulled high.*

In case of a fault condition the DIAG$_X$/EN$_X$ pin is considered an output pin by the device.

The fault conditions are:

- overtemperature on one or both high-sides (for example, if a short to ground occurs as it could be the case described in line 1 and 2 in the *Table 14*);
- Short to battery condition on the output (saturation detection on the low-side Power MOSFET).

Possible origins of fault conditions may be:

- OUT_A is shorted to ground. It follows that, high-side A is in overtemperature state.
- OUT_A is shorted to V_{CC}. It follow that, low-side Power MOSFET is in saturation state.

When a fault condition is detected, the user can know which power element is in fault by monitoring the IN_A, IN_B, $DIAG_A/EN_A$ and $DIAG_B/EN_B$ pins.

In any case, when a fault is detected, the faulty leg of the bridge is latched off. To turn-on the respective output (OUT_X) again, the input signal must rise from low-level to high-level.

Figure 6. Behavior in fault condition (how a fault can be cleared)
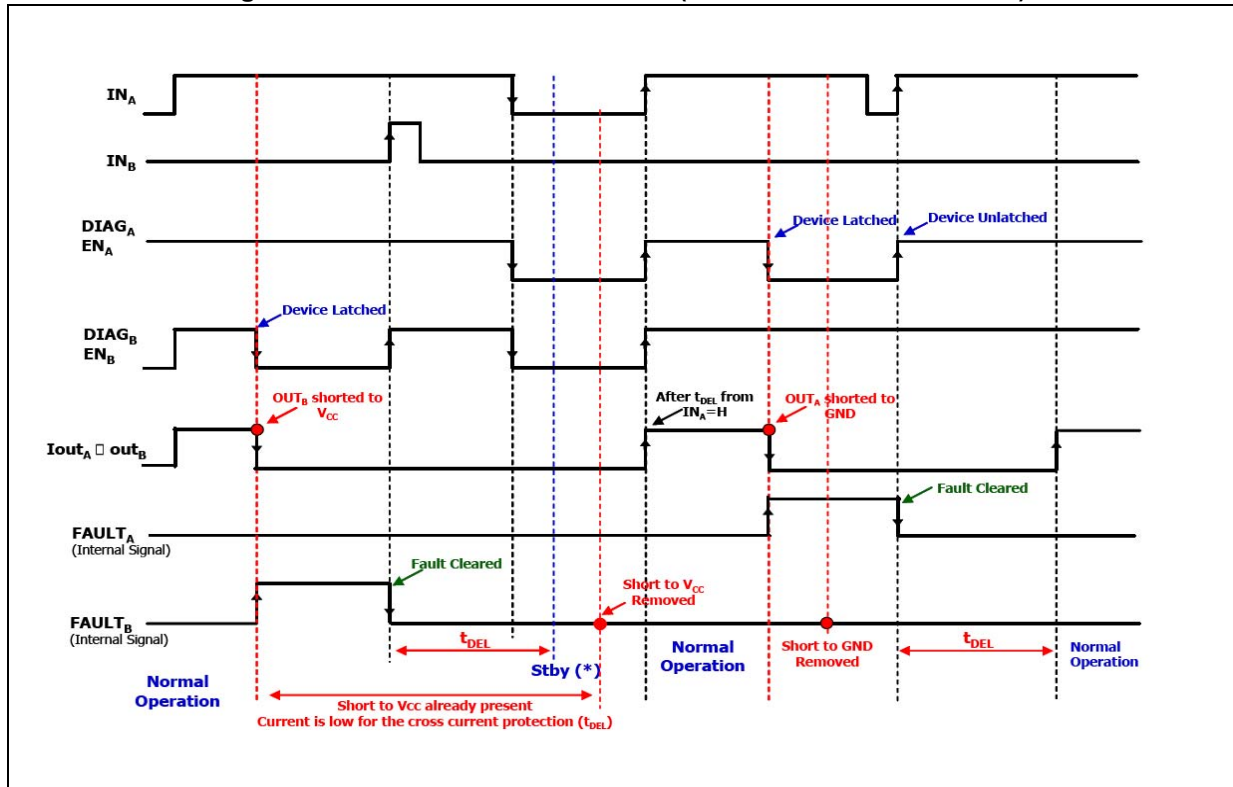
Note: *In case of the fault condition is not removed, the procedure for unlatching and sending the device in Stby mode is:*

- Clear the fault in the device (toggle: INA if ENA=0 or INB if ENB=0)

- Pull low all inputs, PWM and Diag/EN pins within tDEL.

If the Diag/En pins are already low, PWM=0, the fault can be cleared simply toggling the input. The device enters in stby mode as soon as the fault is cleared.

Table 14. Electrical transient requirements (part 1)

ISO T/R 7637/1 Test pulse	Test level				
	I	II	III	IV	Delay and impedance
1	-25 V	-50 V	-75 V	-100 V	2 ms, 10 Ω
2	+25 V	+50 V	+75 V	+100 V	0.2 ms, 10 Ω
3a	-25 V	-50 V	-100 V	-150 V	0.1 μs, 50 Ω
3b	+25 V	+50 V	+75 V	+100 V	0.1 μs, 50 Ω
4	-4 V	-5 V	-6 V	-7 V	100 ms, 0.01 Ω
5	+26.5 V	+46.5 V	+66.5 V	+86.5 V	400 ms, 2 Ω

Table 15. Electrical transient requirements (part 2)

ISO T/R 7637/1 Test pulse	Test levels			
	I	II	III	IV
1	C	C	C	C
2	C	C	C	C
3a	C	C	C	C
3b	C	C	C	C
4	C	C	C	C
5	C	E	E	E

Table 16. Electrical transient requirements (part 3)

Class	Contents
C	All functions of the device are performed as designed after exposure to disturbance.
E	One or more functions of the device are not performed as designed after exposure to disturbance and cannot be returned to proper operation without replacing the device.

2.5   Reverse battery protection

Against reverse battery condition the charge pump feature allows to use an external N-channel MOSFET connected as shown in the typical application circuit (see *Figure 4*).

As alternative option, a N-channel MOSFET connected to GND pin can be used (see typical application circuit in figure *Figure 5*).

With this configuration we recommend to short V_{BAT} pin to V_{CC}.

The device sustains no more than -30 A in reverse battery conditions because of the two body diodes of the power MOSFETs. Additionally, in reverse battery condition the I/Os of VNH5019A-E is pulled-down to the V_{CC} line (approximately -1.5 V). Series resistor must be inserted to limit the current sunk from the microcontroller I/Os. If I_{Rmax} is the maximum target reverse current through microcontroller I/Os, series resistor is:

$$R = \frac{V_{IOs} - V_{CC}}{I_{Rmax}}$$

Figure 7. Definition of the delay time measurement
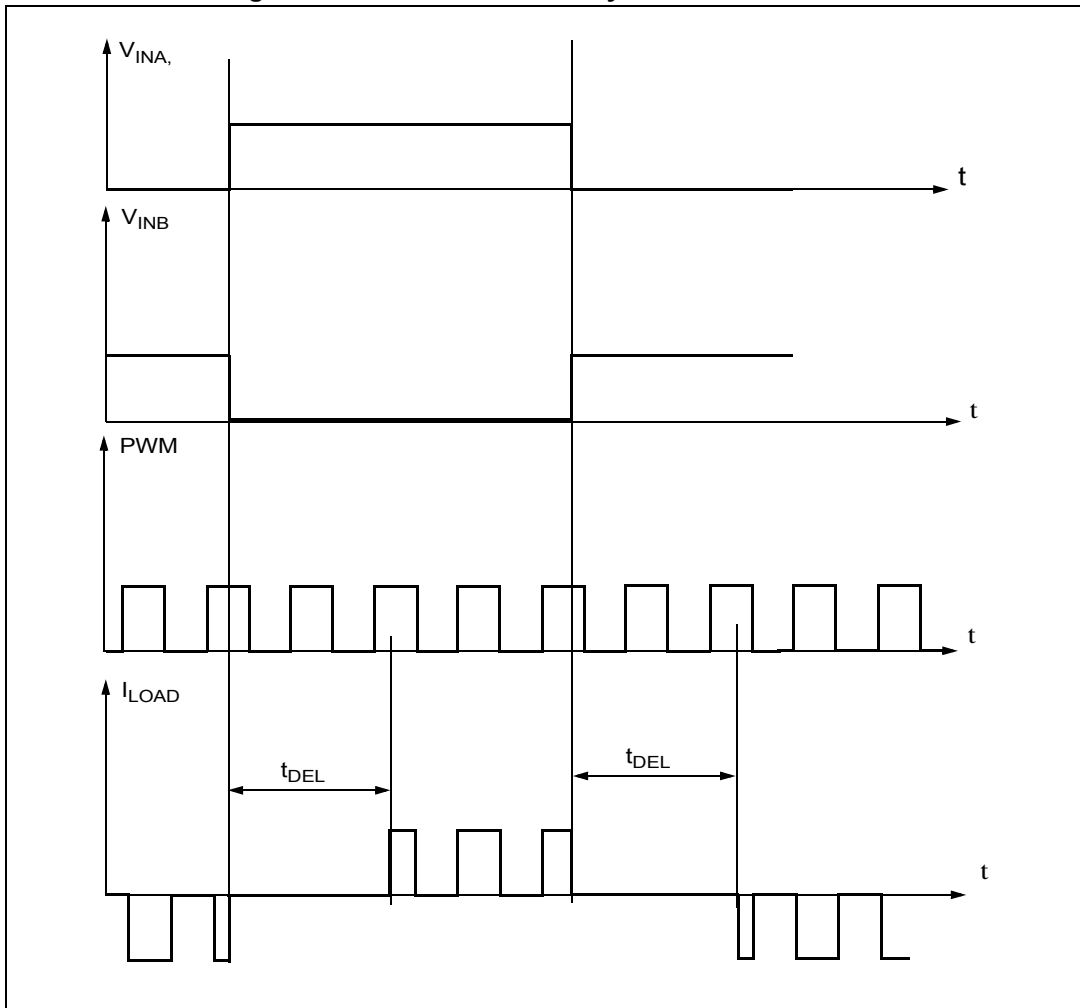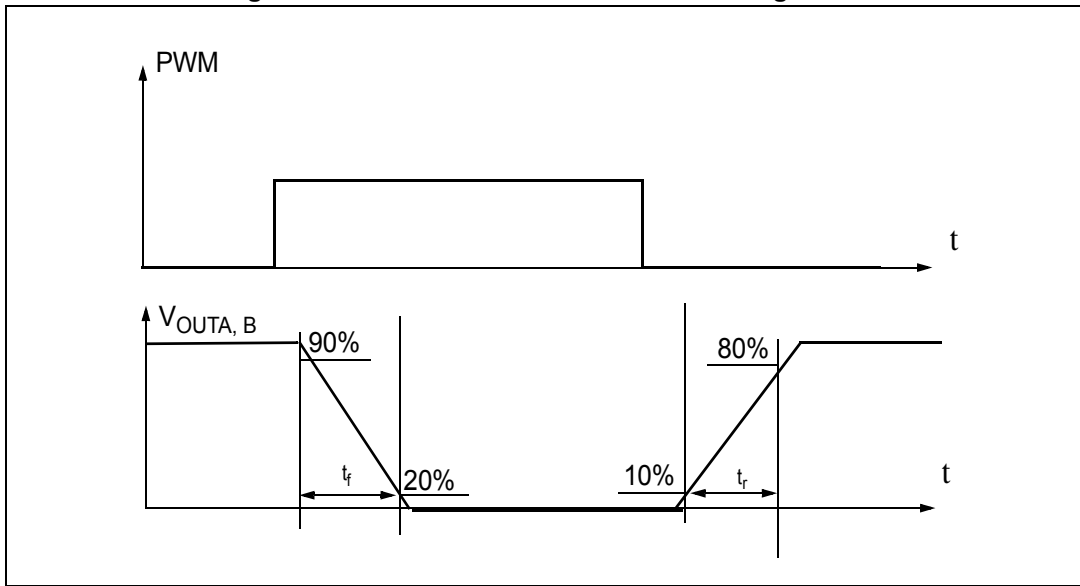
Figure 8. Definition of the low-side switching times

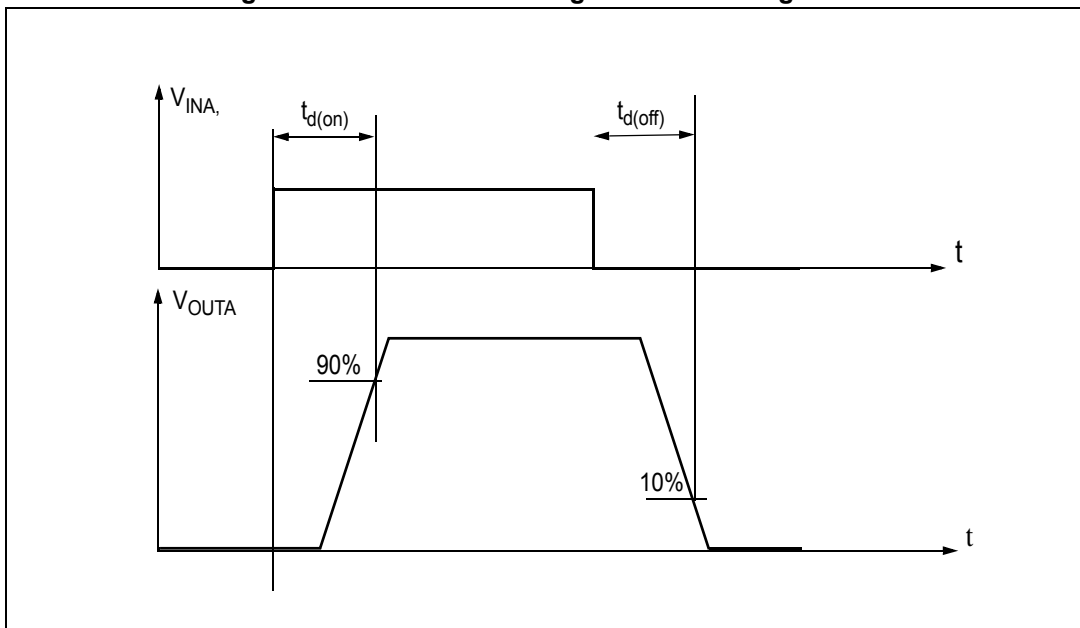**Figure 9. Definition of the high-side switching times**

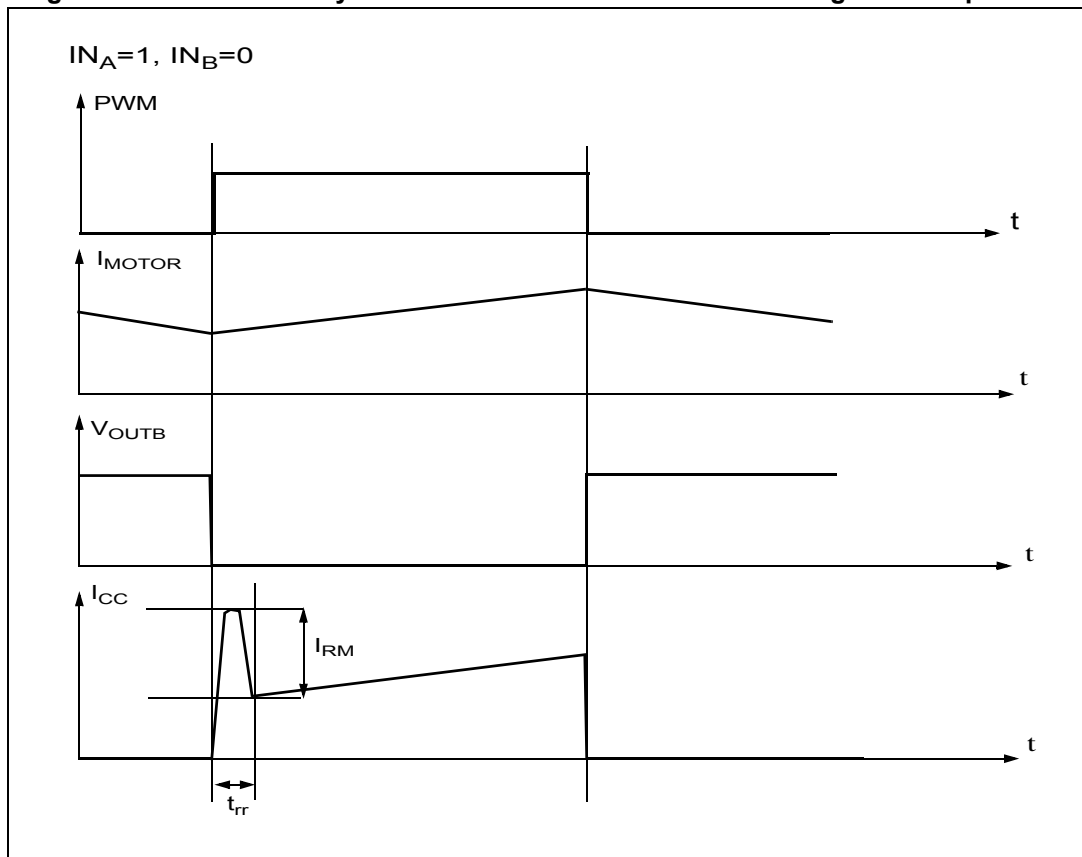**Figure 10. Definition of dynamic cross conduction current during a PWM operation**
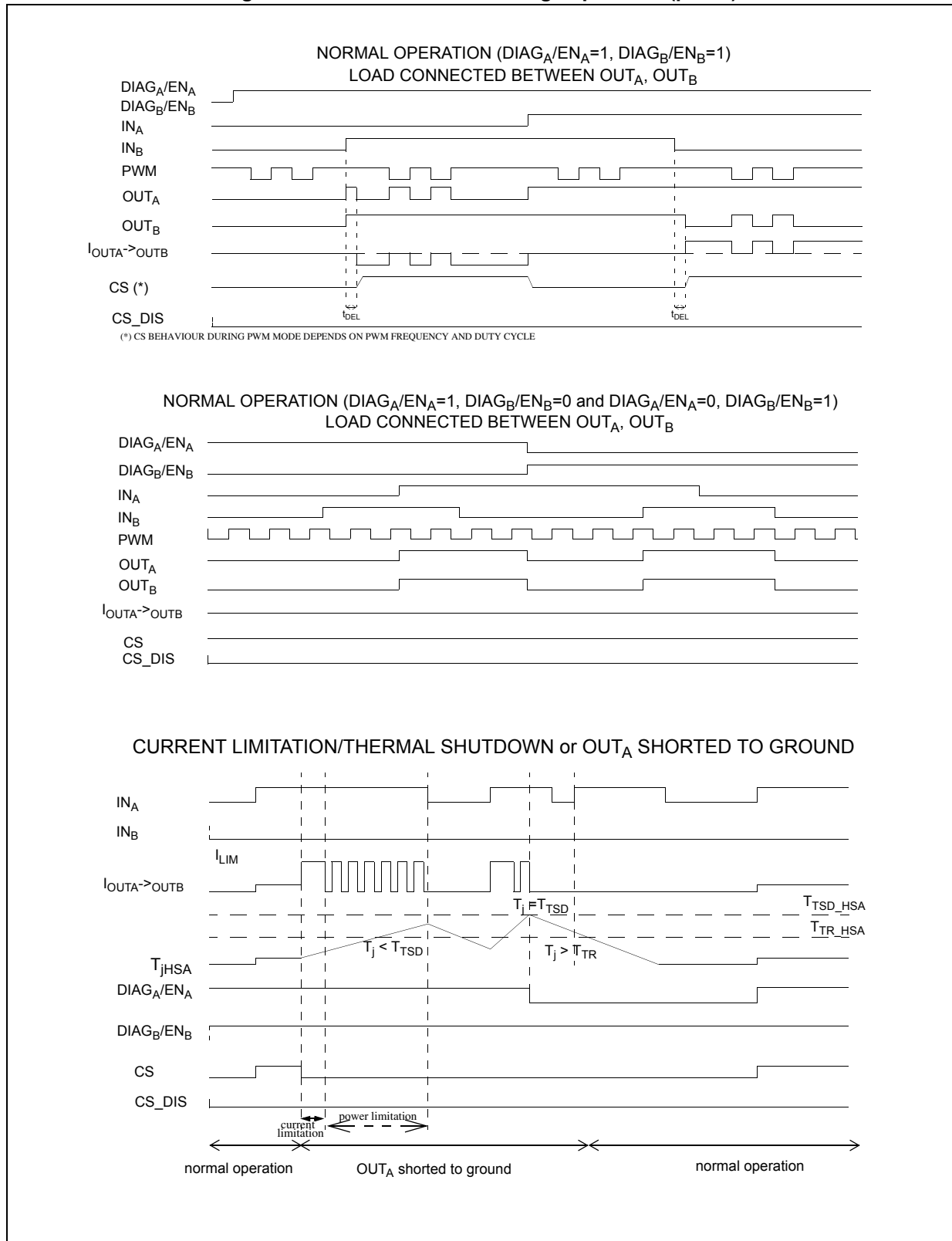
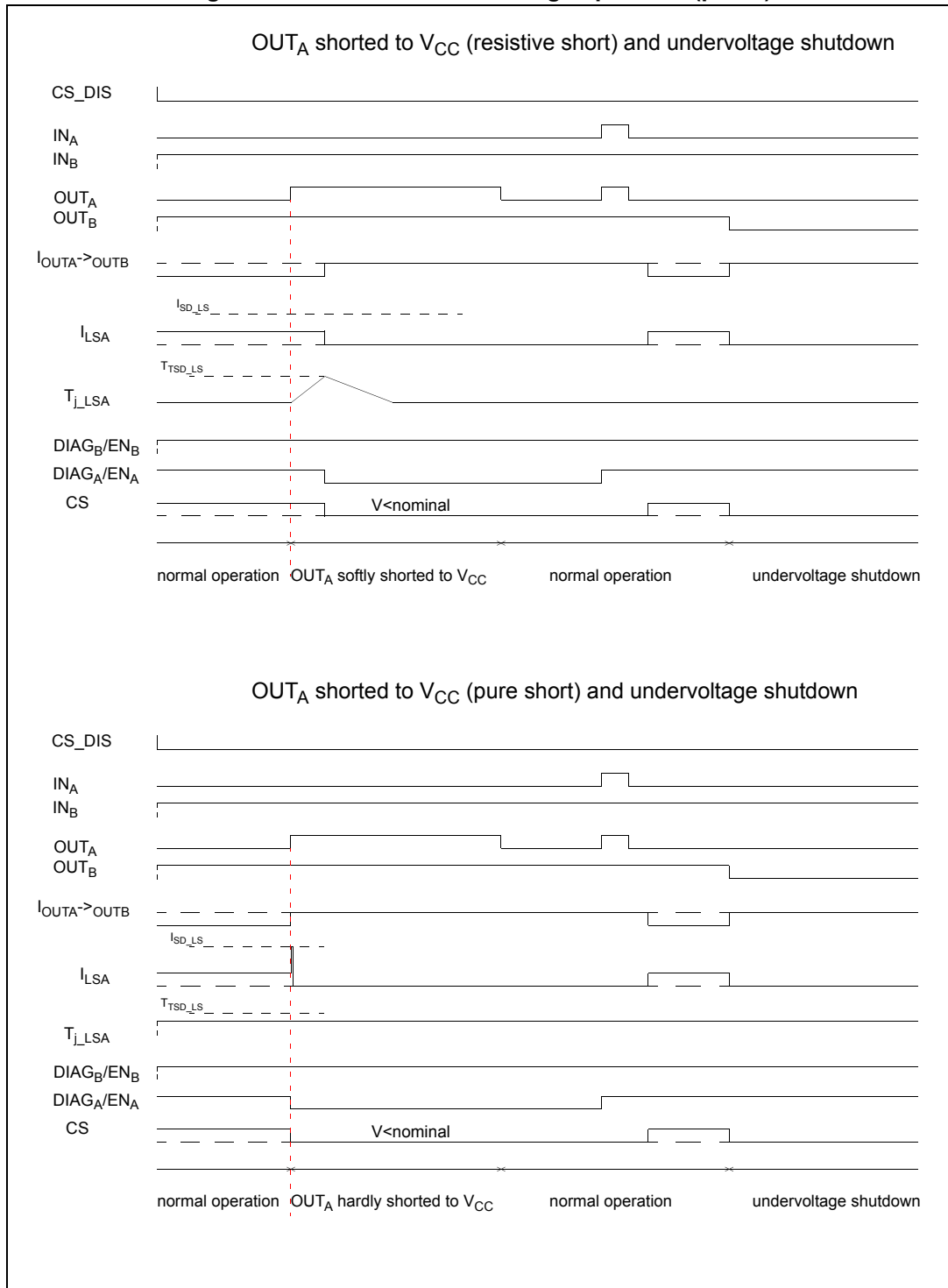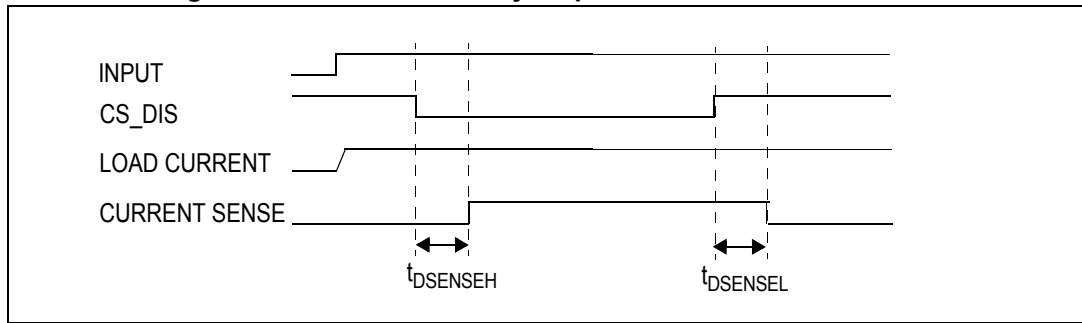**Figure 11. Waveforms in full bridge operation (part 1)**

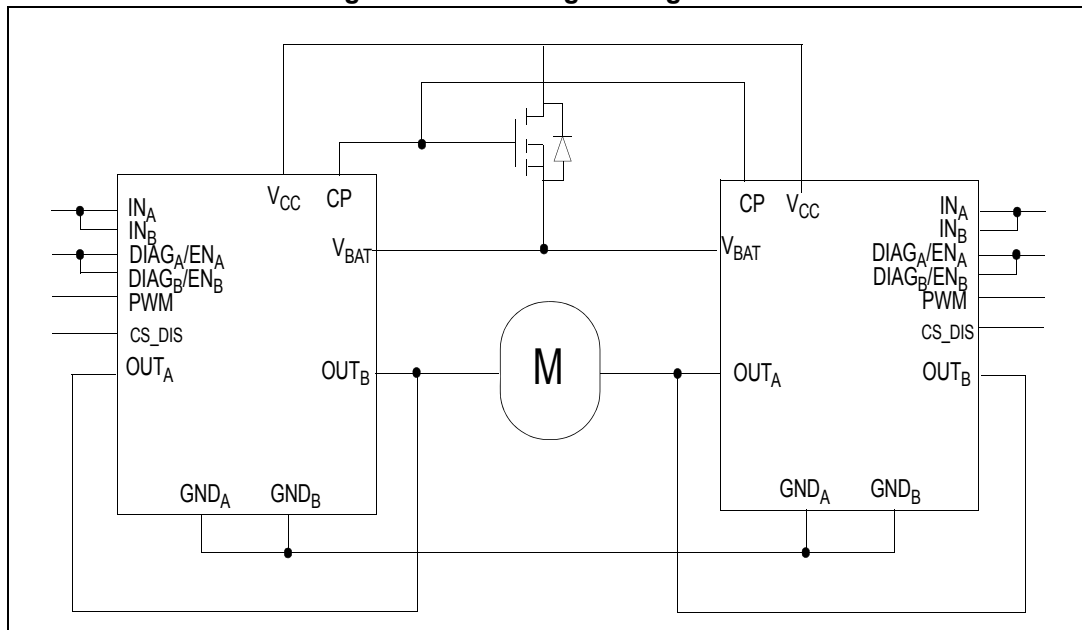**Figure 12. Waveforms in full bridge operation (part 2)**

Figure 13. Definition of delay response time of sense current

The VNH5019A-E can be used as a high power half-bridge driver achieving an on-resistance per leg of 9.5 mΩ. The figure below shows the suggested configuration:

Figure 14. Half-bridge configuration

The VNH5019A-E can easily be designed in multi-motor driving applications such as seat positioning systems where only one motor must be driven at a time. The $DIAG_X/EN_X$ pins allow the unused half-bridges to be put into high-impedance. The diagram that follows shows the suggested configuration:

Figure 15. Multi-motor configuration